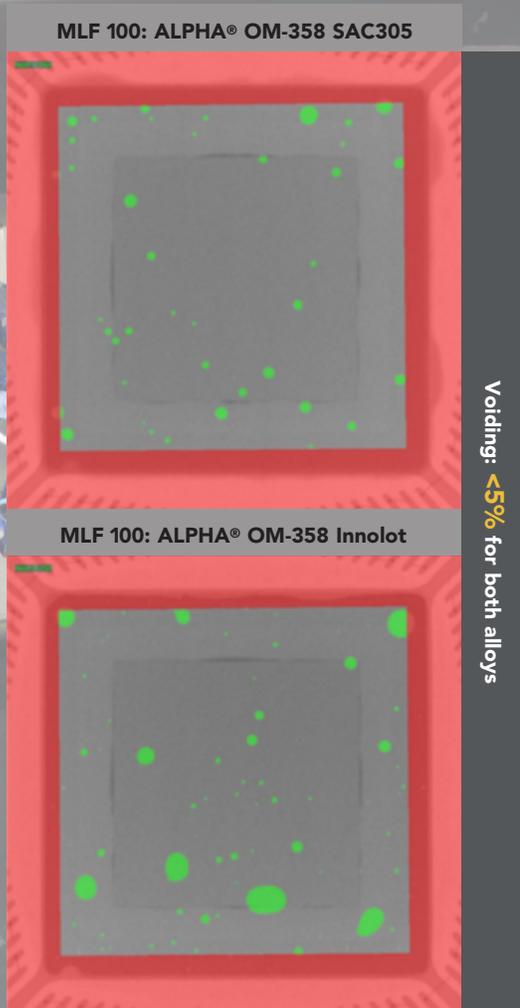


ALPHA® OM-358 ULTRA-LOW VOIDING, HIGH-RELIABILITY, RoHS COMPLIANT, ZERO-HALOGEN, SOLDER PASTE



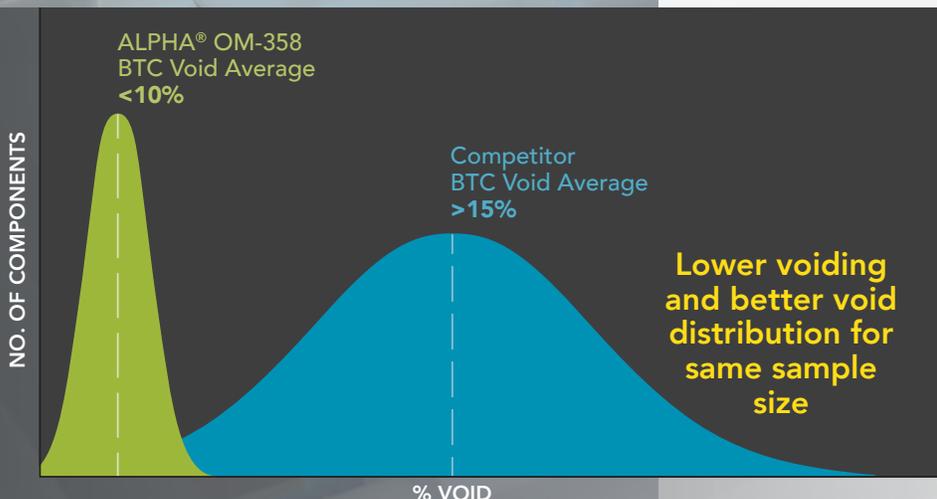
High Reliability Paste from Alpha

ALPHA® OM-358 is a lead-free, zero-halogen, no-clean solder paste designed to provide ultra-low voiding performance on all component types including bottom termination components.

ALPHA® OM-358 achieves IPC Class III voiding on BGA components and less than 10% voiding on bottom termination components. This paste is designed for ultra-low voiding performance with high reliability alloys such as Innolot as well as traditional SAC alloys.

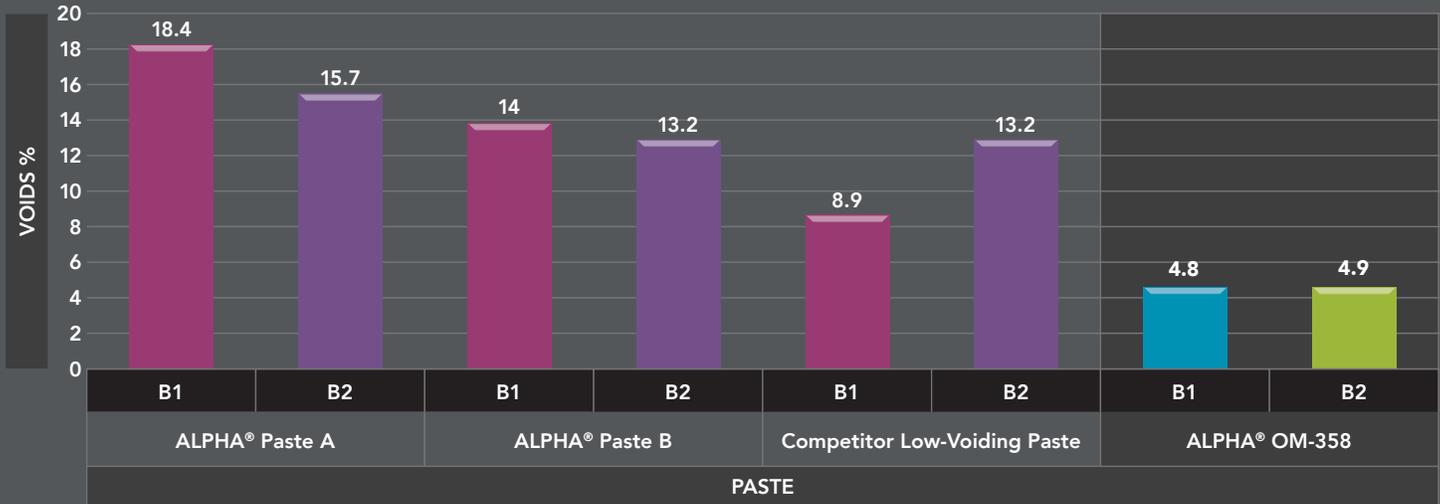
ALPHA® OM-358 Paste

- **Ultra-Low Voiding Performance:** Increases process stability, thermal, and electrical performance of the most demanding component applications.
- **Excellent Electromigration characteristics:** Passes J-STD-004B IPC-TM-650 at 100µm to ensure electrical reliability and functionality of fine-pitched components.
- **Wide Reflow Profile Window:** Enables high quality solderability of complicated, high density PCB assemblies using straight ramp and soak profiles, as high as 150° to 200°C soak.
- **Good Random Solder Ball Levels:** Minimizes rework and increases first pass yield.
- **Good Coalescence and Wetting Performance:** Coalesces down to 170µm exhibiting good wetting characteristics and solder joint reliability.
- **Excellent Solder Joint and Flux Residue Cosmetics:** Easily penetrable and clear flux residue enables good probe contact during quality inspection.



ALPHA® OM-358 ULTRA-LOW VOIDING, HIGH-RELIABILITY, RoHS COMPLIANT, ZERO-HALOGEN, SOLDER PASTE

MLF 100 VOIDS SUMMARY CHART



PERFORMANCE SUMMARY

PROCESS BENEFIT	PROPERTY	PERFORMANCE CAPABILITY
Print Process Window	Fine Feature Print Definition	200µm x 250µm (01005 component, Area Ratio = 0.54)
	Tack/Stencil Life	8 hour stencil life
	Print Speed Range	25-100mm/sec (1-4 in/sec)
Reflow Process Yield	Reflow Environment	Air and Nitrogen
	Resistance to Voids	Meets and exceeds IPC Class III requirements
	Random Solder Balls	Passes – IPC J-STD-005A Criteria – Preferable
	Residue Profile	Clear
	Coalescence	Good coalescence down to 170 microns
Electrical Reliability	Flux Residue Characteristics	Clear, soft, and pin-testable
	IPC SIR	Passes J-STD-004B TM 2.6.3.7
	Electromigration	Passes IPC-TM-650 Method 2.6.14.1
Environmental	Classification	ROLO as per J-STD-004B
	Halogen Content	Zero-Halogen



* Zero Halogen is defined as no halogen intentionally added to the formulation.

For more information about ALPHA® OM-358 Ultra-Low Voiding, High-Reliability, RoHS Compliant, Zero-Halogen, Solder Paste, please contact your Alpha Representative.

AlphaAssembly.com

Global Headquarters
300 Atrium Drive
Somerset, NJ 08873
USA
Tel: +1-814-946-1611

European Headquarters
Unit 2, Genesis Business Park
Albert Drive, Woking, Surrey, GU21 5RW
UK
Tel: +44 (0) 1483 758400

Asia/Pacific
8/F, Paul Y. Centre, 51 Hung To Road
Kwun Tong, Kowloon
Hong Kong
Tel: 852-3190-3100